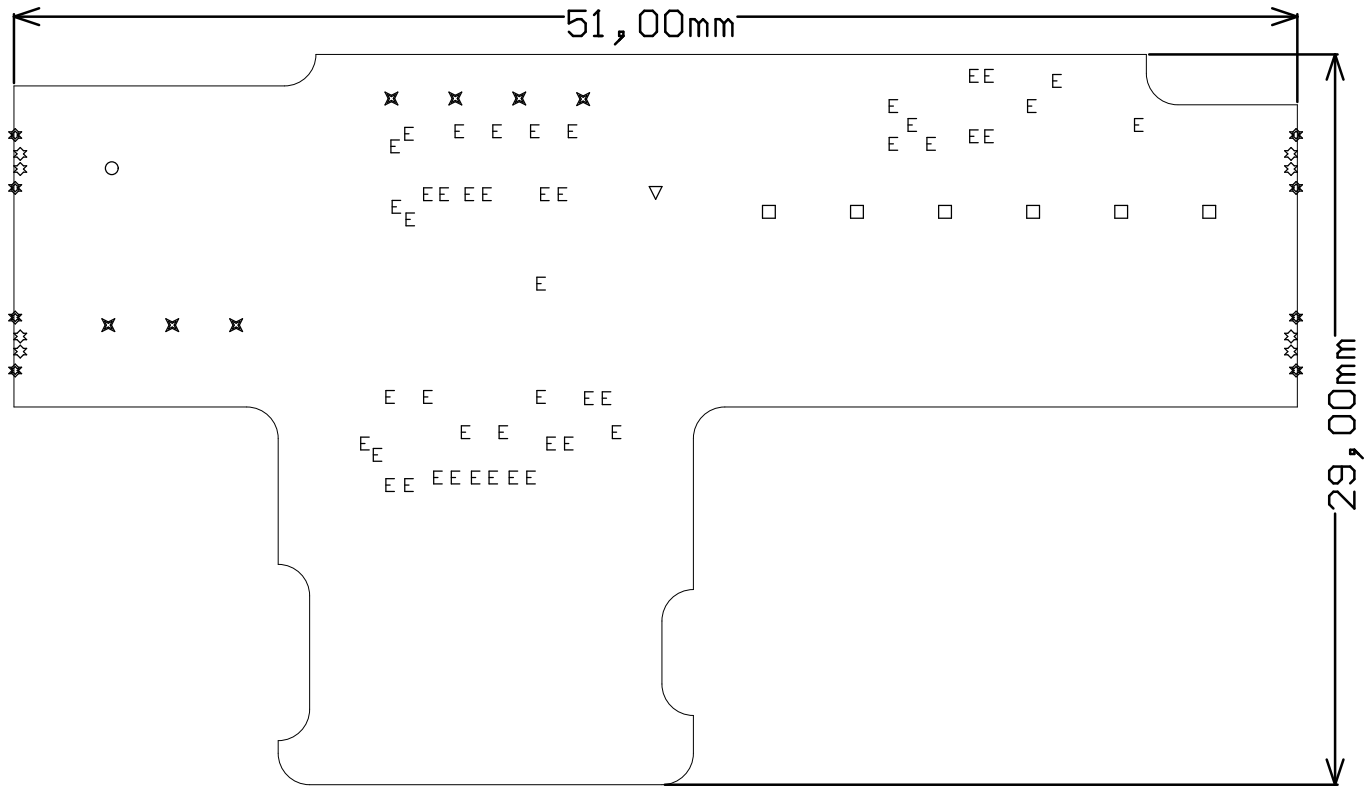


Layer Stackup 4 FR4		
Top Soldermask	25 um	standard
Layer1 Top	35 um	Signal
Prepreg	300 um	
Layer2	35 um	Plane
Core	710 um	
Layer3	35 um	Plane
Prepreg	300 um	
Layer4 Bottom	35 um	Plane
Bottom Soldermask	25 um	standard
Thickness approx.	1500 um	



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
E	46	0,200mm (7,87mil)	PTH	Round	Layer1 Top - Layer4 Bottom			-	-
☆	8	0,400mm (15,75mil)	NPTH	Round	Layer1 Top - Layer4 Bottom			-	-
▽	1	0,650mm (25,59mil)	PTH	Round	Layer1 Top - Layer4 Bottom			-	-
★	8	0,800mm (31,50mil)	NPTH	Round	Layer1 Top - Layer4 Bottom			-	-
✕	7	1,000mm (39,37mil)	PTH	Round	Layer1 Top - Layer4 Bottom			-	-
□	6	1,200mm (47,24mil)	PTH	Round	Layer1 Top - Layer4 Bottom			-	-
○	1	2,900mm (114,17mil)	PTH	Round	Layer1 Top - Layer4 Bottom			-	-
	77 Total								

All drills (PTH and NPTH) should run in one work process

Title: CSI2-NITROGEN_Rev01		Allied Vision Technologies		Taschenweg 2a	Germany	Bare Board Revision: 01	
Project: CSI2-NITROGEN	PCB Designer: OFU		Layer Name: Drill Drawing			Bare Board Number:	
Date: 27.11.2019	File Name: CSI2-NITROGEN_Rev01.PcbDoc			SCALE: 1.00			